

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants : Jie-Wei Chen et al. Confirmation No.:  
Serial No. :  
Filed :  
TC/A.U. :  
Examiner :

Docket No. : 03-494  
Customer No. : 34704

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313

INFORMATION DISCLOSURE STATEMENT

Dear Sir:

In accordance with the requirements of 37 CFR 1.97 and 1.98, Applicants hereby submit the documents listed hereinbelow, copies enclosed.

- (1) European Patent No. 0 997 261 entitled LASER BONDING OF PLASTIC WORKPIECES COMPRISES USING..., By Chen, published May 3, 2000. This patent is in German however an English abstract is not attached.

The undersigned submits the above-identified references for independent consideration by the Examiner and does not make any admission that these references are or are not material to

the present invention or that these references are or are not prior art with respect to the present invention.

Respectfully submitted,


Jie-Wei Chen et al.

By 

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Date: September 22, 2003

I hereby certify that this correspondence is being deposited with the United States Postal Service as Express Mail in an envelope addressed to: "Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313" on September 22, 2003.

  
Rachel Pisatelli

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PTO/SB/08A (08-00)

Approved for use through 10/31/2002. OMB 0651-0031  
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Substitute for form 1449A/PTO  <b>INFORMATION DISCLOSURE STATEMENT BY APPLICANT</b>  <i>(use as many sheets as necessary)</i>				<b>Complete if Known</b>	
				Application Number	
				Filing Date	
				First Named Inventor	Jie-Wei Chen et al.
				Group Art Unit	
				Examiner Name	
Sheet	1	of	1	Attorney Docket Number	03-494

U.S. PATENT DOCUMENTS						
Examiner Initials *	Cite No. <sup>1</sup>	U.S. Patent Document		Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear
		Number	Kind Code <sup>2</sup> (if known)			

FOREIGN PATENT DOCUMENTS								
Examiner Initials *	Cite No. <sup>1</sup>	Foreign Patent Document			Name of Patentee or Applicant of Cited Document	Date of Publication of Cited Document MM-DD-YYYY	Pages, Columns, Lines, Where Relevant Passages or Relevant Figures Appear	T <sub>6</sub>
		Office <sup>3</sup>	Number <sup>4</sup>	Kind Code <sup>5</sup> (if known)				
		EP	0 997 261		Chen	05-03-2000		

Examiner Signature		Date Considered	
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\*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

<sup>1</sup> Unique citation designation number. <sup>2</sup> See attached Kinds of U.S. Patent Documents. <sup>3</sup> Enter Office that issued the document, by the two-letter code (WIPO Standard ST.3). <sup>4</sup> For Japanese patent documents, the indication of the year of the reign of the Emperor must precede the serial number of the patent document. <sup>5</sup> Kind of document by the appropriate symbols as indicated on the document under WIPO Standard ST. 16 if possible. <sup>6</sup> Applicant is to place a check mark here if English language Translation is attached.

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